PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
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WATARU HIRASAWA	04/18/2003
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RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	8878244

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NAME OF SUBMITTER:	JOHN R. MATTINGLY
SIGNATURE:	/John R. Mattingly/
DATE SIGNED:	05/11/2017

Total Attachments: 1
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ASSIGNMENT
（譲 渡 証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi, Ltd.,
and Renesas Eastern Japan Semiconductor, Inc.,
corporations organized under the laws of Japan,
located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan,
and 3-2, Fujihashi 3-chome, Ome-shi, Tokyo, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,
and Renesas Eastern Japan Semiconductor, Inc.,
their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

FABRICATION METHOD OF SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Pater which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd.,
and Renesas Eastern Japan Semiconductor, Inc.,
their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said
Hitachi, Ltd., and Renesas Eastern Japan Semiconductor, Inc.,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Yasuichi Kondo Yasuichi KONDO	18/April/2003
2)	Wataru Hirasawa Wataru HIRASAWA	18/April/2003
3)	Nobuyuki Sugii Nobuyuki SUGII	24/April/2003
4)		
5)		
6)		
7)		
8)		
9)		
10)		